Amendments to the Claims

This listing of claims will replace all prior listings of claims in the application.

Listing of Claims

1.-18. (Canceled)

19. (Currently Amended) The plated resin molded article according to ~~claim 30~~claim 31, wherein the surfactant comprises an emulsifying agent that is used in emulsion polymerization.

20. (Currently Amended) The plated resin molded article according to ~~claim 30~~claim 31, wherein the maximum value of the adhesive strength, according to JIS H8630, between the thermoplastic resin molded article and the metal plating layer is at least 10 kPa.

21. (Currently Amended) The plated resin molded article according to ~~claim 30~~claim 31, applied as an automotive component.

22. (Withdrawn) A method of producing a plated resin molded article according to claim 30, wherein the plated resin molded article is produced by plating metal on the surface of the thermoplastic resin molded article, the method comprising the step of contact-treating the thermoplastic resin molded article with an acid or base that does not contain a heavy metal, as a treatment preceding a metal plating step, and wherein a step of etching with a heavy metal-containing acid is not included.

23. (Withdrawn) The method of producing a plated resin molded article according to claim 22, comprising the steps of:

removing fat of the thermoplastic resin molded article; contact-treating the thermoplastic resin molded article with an acid or base that does not contain heavy metal; and a plating step, wherein the method does not include a step of etching with a heavy metal-containing acid.

24. (Withdrawn) The method of producing a plated resin molded article according to claim 22, comprising the steps of: removing fat of the plastic resin molded article; contact-treating the thermoplastic resin molded article with an acid or base that does not contain a heavy metal; treating the thermoplastic resin molded article with a catalyst-imparting liquid; and a plating step, wherein the method does not include a step of etching with a heavy metal-containing acid.

25. (Withdrawn) The method of producing a plated resin molded article according to claim 22, wherein the concentration of the acid or base used in the step of contact-treating with an acid or base that does not contain a heavy metal is less than 4 normal.

26. (Withdrawn) The method of producing a plated resin molded article according to claim 22, wherein the step of contact-treating with an acid or base that does not contain a heavy metal is a step of immersing the thermoplastic resin molded article in acid or base that does not contain heavy metal.

27. (Withdrawn) The method of producing a plated resin molded article according to claim 22, wherein the step of contact treating with an acid or base that does not contain a heavy metal is a step of immersing the thermoplastic resin molded article for 20 to 0.5 minutes at a liquid temperature of 10 to 80°C in an acid or base that does not contain a heavy metal.

28. (Withdrawn) The method of producing a plated resin molded article according to claim 22, wherein the acid that does not contain a heavy metal is selected from hydrochloric acid, phosphoric acid, sulfuric acid and organic acids.

29. (Withdrawn) The method of producing a plated resin molded article according to claim 22, wherein the base that does not contain a heavy metal is selected from hydroxides of an alkali metal or alkali earth metal.

30. (Canceled)

31. (Currently Amended) A plated resin molded article that has a metal plating layer provided on the surface of a thermoplastic resin article formed from a composition comprising the following components:

(A) 10 to 90 mass % of a matrix resin that has a water absorption after 24 hours in 23°C water, according to ISO62, of at least 0.6%;

(B) 90 to 10 mass % of a polyphenylene ether-based resin;

(C) a water-soluble substance having a solubility at 25°C of not more than 300g in 100g of water and selected from the group consisting of pentaerythritol and dipentaerythritol in an amount of 0.01 to 50 mass parts per 100 mass parts of the sum of components (A) and (B); ~~and at least one member selected from the group consisting of~~

(D) at least one of a surfactant and a coagulant in an amount of 0.01 to 10 mass parts per 100 mass parts of the sum of components (A) and (B); and

(E) a phosphorus compound comprising one or more members selected from the group consisting of a condensed phosphate ester, an aliphatic acid aromatic phosphate ester of an orthophosphate ester, an alkali metal salt of melamine polyphosphate tripolyphosphoric acid, pyrophosphoric acid, orthophosphoric acid or hexametaphosphoric acid and phytic

acid, an alkali metal salt thereof and an alkanolamine salt thereof in an amount of 0.1 to 30 mass parts per 100 mass parts of the sum of components (A) and (B).

32. (Currently Amended) The plated resin molded article according to ~~Claim 30~~claim 31, wherein the water-soluble substance (C) is present in an amount of from 0.01 to 15 mass parts per 100 mass parts of the sum of components (A) and (B).

33. (Previously Presented) The plated resin molded article according to Claim 31, wherein the water-soluble substance (C) is present in an amount of from 0.01 to 10 mass parts per 100 mass parts of the sum of components (A) and (B) and a surfactant (D) is present in an amount of from 0.01 to 10 mass parts per 100 mass parts of the sum of components (A) and (B).

34. (Previously Presented) The plated resin molded article according to Claim 33, additionally comprising a phosphorus compound (E) in an amount of 0.1 to 10 mass parts per 100 mass parts of the sum of components (A)+(B).

35. (Previously Presented) The plated resin molded article according to Claim 32, wherein component (A) is polyamide 6, component (B) is poly(2,6-dimethyl-1,4-phenylene ether) and component (C) is dipentaerythritol.

36. (Previously Presented) The plated resin molded article according to Claim 33, wherein component (A) is polyamide 6, component (B) is poly(2,6-dimethyl-1,4-phenylene ether), component (C) is dipentaerythritol and component (D) is an α-olefin sulfonate.

37. (Previously Presented) The plated resin molded article according to Claim 34, wherein component (A) is polyamide 6, component (B) is poly(2,6-dimethyl-1,4-phenylene

ether), component (C) is dipentaerythritol, component (D) is an α-olefin sulfonate and component (E) is triphenyl phosphate.

38. (New) The plated resin molded article according to claim 31, wherein the condensed phosphate esters are selected from the group consisting of triphenyl phosphate, tricresyl phosphate, trixylenyl phosphate, tris(isopropylphenyl) phosphate, tris(o- or p-phenylphenyl) phosphate, trinaphthyl phosphate, cresyl diphenyl phosphate, xylenyl diphenyl phosphate, di(isopropylphenyl) phenyl phosphate, o-phenylphenyl dicresyl phosphate, tris(2,6-dimethylphenyl) phosphate, tetraphenyl m-phenylene diphosphate, tetraphenyl p-phenylene diphosphate, phenyl resorcinol polyphosphate, bisphenol A-bis(diphenyl phosphate), bisphenol A-polyphenyl phosphate and dipyrocatechol hypodiphosphate.

39. (New) The plated resin molded article according to claim 31, wherein the aliphatic acid-aromatic phosphate ester of an orthophosphate ester is selected from the group consisting of diphenyl (2-ethylhexyl) phosphate, diphenyl 2-acryloyloxyethyl phosphate, diphenyl 2-methacryloyloxyethyl phosphate, diphenyl neopentyl phosphate, pentaerythritol diphenyl diphosphate and ethyl pyrocatechol phosphate.

40. (New) The plated resin molded article according to claim 31, wherein the condensed phosphate esters are triphenyl phosphate.

41. (New) The plated resin molded article according to claim 31, wherein (A) the matrix resin is selected from the group consisting of a polyamide resin, an acrylate salt resin, a cellulose resin, a vinyl alcohol resin and a polyether resin.

42. (New) The plated resin molded article according to claim 31, wherein (A) the matrix resin is a polyamide resin.

43. (New) The plated resin molded article according to claim 31, wherein (A) the matrix resin is selected from the group consisting of nylon 66, polyhexamethylenesebacamide, polyhexamethylenedodecanamide, a polydodecamethylenedodecanamide (nylon 12, 12), polymethaxylyleneadipamide, polytetramethyleneadipamide, and a mixture thereof and a copolymer; copolymers such as a nylon 6/66, a nylon 66/6T in which a 6T component is 50% by mol or less (6T: polyhexamethyleneterephthalamide), a nylon 66/6I in which a 6I component is 50% by mol or less (6I: polyhexamethyleneisophthalamide), a nylon 6T/6I/66 and a nylon 6T/6I/610; copolymers of a polyhexamethyleneterephthalamide (nylon 6T), a polyhexamethyleneisophthalamide (nylon 6I), a poly(2-methylpentamethyelene)terephthalamide (nylon M5T), a poly(2-methylpentamethylene)isophthalamide (nylon M5I), a nylon 6T/6I or a nylon 6T/M5T.

44. (New) The plated resin molded article according to claim 31, wherein (A) the matrix resin is selected from the group consisting of polyamide 6, polyamide 66 and polyamide 6/66.

45. (New) The plated resin molded article according to claim 31, wherein (D) the coagulant is different from those which are used in the emulsion polymerization.

46. (New) The plated resin molded article according to claim 31, wherein (D) the coagulant is selected from those which are used in the emulsion polymerization and those which are not used in the emulsion polymerization.

47. (New) The plated resin molded article according to claim 31, wherein (D) the surfactant is an anionic surfactant,

a cationic surfactant, a nonionic surfactant or an amphoteric surfactant.

48. (New) The plated resin molded article according to claim 31, wherein (D) the surfactant is selected from the group consisting of a salt of an aliphatic acid, a salt of rosin acid, an alkyl sulfonate, an alkylbenzene sulfonate, an alkyldiphenyl ether sulfonate, a polyoxyethylenealkyl ether sulfonate, a diester salt of sulfosuccinic acid, an ester salt of α-olefin sulfonic acid and an α-olefin sulfonate; a mono or dialkylamine or a polyoxyethylene adduct thereof and a mono or di-long chain alkyl quaternary ammonium salt; and an alkyl glucoside, a polyoxyethylenealkyl ether, a polyoxyethylenealkyl phenyl ether, sucrose ester of an aliphatic acid, a sorbitan ester of an aliphatic acid, a polyoxyethylene sorbitan ester of an aliphatic acid, a polyoxyethylene ester of an aliphatic acid, a polyoxyethylene-propylene block copolymer, a mono glyceride of an aliphatic acid and amine oxide, carbobetaine, sulfobetaine and hydroxysulfobetaine.

49. (New) The plated resin molded article according to claim 31, wherein (D) the surfactant is an α-olefin sulfonate.

50. (New) The plated resin molded article according to claim 31, wherein (E) the condensed phosphate ester is triphenyl phosphate and (A) the matrix resin is a polyamide resin.